

Bonder

BS-03

ACF Equipment Partner

OHASHI

OHASHI Engineering. Co., Ltd.



Compared to the old BS-01:

- 9.1% smaller footprint
- Compact head design
- Better ergonomics

Process

Bonding (Constant)

Multiple-head constant heat bonder

Equipment Overview

The BS-03 is a semiautomatic constant heat bonder with multiple heads (2-4). Each head is independently controlled and bonds a single ACF site on the array of substrates loaded within the carrier.

Equipment dimension	W x D x H
	800 x 1000 x 2080 (mm)
Weight	~ 700 Kg

Number of operators	1 person
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Productivity

Varies greatly depending on # of heads. TYP 2.5-3.0 seconds.
Speak with your supplier for more information

Highly-Efficient Multiple Head System

One row of assemblies in the carrier is bonded during each cycle, allowing high throughput.

Toolless Head Changeover

The bonding heads can be changed without using tools, making for faster product changeover times.

Common Carrier System

The carrier used by the BS-03 is the same common carrier used by the LS-02, MS-04, BS-04, and other units in Ohashi's semiautomatic line of equipment.

Ease of Use

The BS-03 incorporates a pokayoke sensor in the stage to eliminate bonding when no work is present.

Safety

This equipment is CE certified.

Spec. overview

Carrier Size (W)250 x (D)400mm

Tool Size Max. (W)30 x (D)8mm

Utilities	Compressed air 0.5Mpa Internal vacuum source 3 Φ 200-220V 50/60Hz 2KVA
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of Bond Heads 2-4 heads

Bond Tolerance TYP ±10um

Interposer Feed Auto-winding

Manufacturer



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Distributor



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